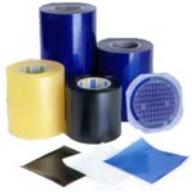


Semiconductor Equipment Corporation

Product Line Shortform



Semiconductor Wafer Dicing Tape
Available in low, medium and high tack or no tack. Available in various size rolls and squares.



UV Curable Dicing Tape
A very high adhesive strength secures wafers firmly during dicing, while yet allowing for easy removal after exposure.



Model 360 UV Exposure System
Revolutionary new design cures UV tapes quickly and uniformly, has an ultra long light source life & handles all size wafers up to 300mm.



Models 300 / 3150 / 3100 Wafer/Frame Tape Applicators
Mounts all size wafers and other substrates onto film frames for dicing.



Models 3200 / 3250 Wafer/Backlap Applicator
Applies protective tape to your wafer prior to backlapping.



Model 450 Hot Gas Rework Station
Hot gas rework station removes surface mounted components and bonded die.



Model 430 Hot Gas Module
Hot gas jet directs up to 800 degrees Celsius through an interchangeable nozzle to a specific area.



Yamaha i-CUBE II Die Mounter
This automatic high-speed and precision bonder is capable of mixed mounting SMD and semiconductor components as well as handling multiple types of component feeders.



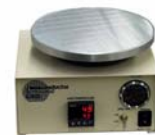
Model 850 Flip Chip Die Bonder
A versatile, semi-automatic system for flip chips, chip scale devices and bare die. Good for low volume production.



Model 860 Omni Die Bonder
A multi-use system, which can be configured to bond laser diodes, flip chip and eutectic bonded die.



Model 830 Pick & Place System
General purpose pick and place system for die and surface mount components. Transfers die from tape to wafer packs. Epoxy dispense option.



Model 4800 Die Ejector Grid
Die ejector grid system for loosening die for quick, safe removal from mounting tape.



Model 4750 Die Ejector
Pokes die off of dicing tape. Especially useful for small die.



Condor Multifunctional Bond Tester
Performs wire pull, bond shear, die shear to 200 kg without the need to change load cell.

Semiconductor Equipment Corporation

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